

FORM PTO-1449 (Modified)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 06318 USA	SERIAL NO.
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)		APPLICANT William Franklin Burgoyne, Jr., et al.	
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(37 CFR 1.98(b))

U.S. PATENT DOCUMENTS

EXAM- INER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
					YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	J. H. Lau, "A Brief Introduction Flip Chip Technologies for Multichip Module Applications," <i>Flip Chip Technologies</i> , Mc-Graw Hill, New York (1995)
	R. Tummala, "Microelectronics Packaging – An Overview," <i>Microelectronics Handbook, Part 1</i> , Ed. International Thompson Publishing, 2 nd Edition, New York (1997)
	K. Gilleo, "Introduction to Conductive Adhesive Joining Technology," <i>Conductive Adhesives for Electronics Packaging</i> , Electrochemical Publications, British Isles (1999)
	R. Ghaffarian, "Close the Information Gap on IC-Package Reliability," <i>Electronic Design</i> , Vol. 46, No. 18, pp. 71-72 (Aug. 3, 1998)
	J. Ivan, et al., "Moisture and Thermal Degradation of Cyanate-Ester-Based Die Attach Material," <i>Proceedings of the 1997 Electronic Components and Technology Conference</i> , 1997, pp. 525-535
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	D. P. Galloway, et al., "Reliability of Novel Die Attach Adhesives for Snap Curing," <i>Proceedings of the IEEE/CPMT International Electronic Manufacturing Technology (IEMT) Symposium</i> , 1995, pp. 141-147
	A. Javidinejad, et al., "Application of Electrically Conductive Thermoplastic Adhesive Film for Design and Manufacturing of Smart Structures," <i>SPIE Proceedings Smart Structures and Integrated Systems</i> , Vol. 3668, March 1999, pp. 688-695
	D. Lu, et al., "Conductive Adhesives Based on Anhydride-Cured Epoxy Systems," <i>Proceedings of the 2nd International IEEE Symposium on Polymeric Electronics Packaging</i> , 1999
	K. Gilleo, "Assembly With Conductive Adhesives," <i>Soldering and Surface Mount Technology</i> , No. 19, Feb. 1995, pp. 12-17
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	J. Jagt, "Reliability of Electrically Conductive Adhesive Joints for Surface Mount Applications," <i>IEEE Transactions on Components, Packaging and Manufacturing Technology – Part A</i> , Vol. 21, No. 2, pp. 215-225 (June 1998)

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